Global Advanced Packaging Market Data Survey Report 2025

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Abstracts

Summary

During the final stages of semiconductor development, a tiny block of materials (the silicon wafer, logic, and memory) is wrapped in a supporting case that prevents physical damage and corrosion and allows the chip to be connected to a circuit board. Typical packaging configurations have included the leadless chip carriers and pin-grid arrays of the 1980s, the system-in-package and package-on package setups of the 2000s, and, most recently, 2-D integrated-circuit technologies such as wafer-level, flip-chip, and through silicon via setups.
The global Advanced Packaging market will reach Volume Million USD in 2017 with CAGR xx% 2018-2025. The main contents of the report including:

Global market size and forecast

Regional market size, production data and export & import

Key manufacturers (manufacturing sites, capacity and production, product specifications etc.)

Average market price by SUK

Major applications

Key manufacturers are included based on manufacturing sites, capacity and production, product specifications etc.:

ASE

Amkor

SPIL

Stats Chippac

PTI

JCET

J-Devices

UTAC

Chipmos

Chipbond

STS

Huatian

NFM

Carsem

Walton

Unisem

OSE

AOI

Formosa

NEPES

Major applications
as follows:

- Analog & Mixed Signal
- Wireless Connectivity
- Optoelectronic
- MEMS & Sensor
- Misc Logic and Memory
- Others

Regional market size, production data and export & import:

- Asia-Pacific
- North America
- Europe
- South America
- Middle East & Africa

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